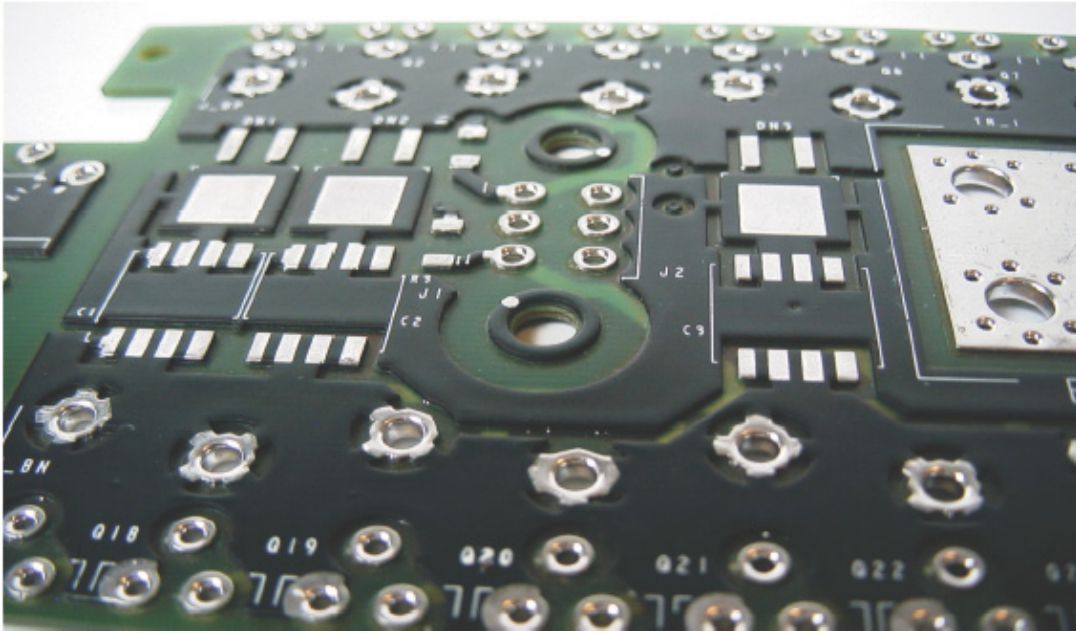


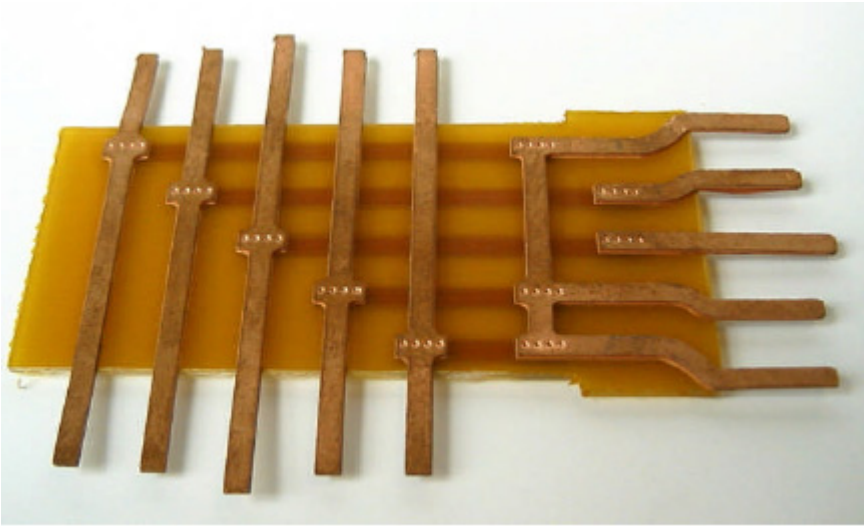
Heavy Copper Design



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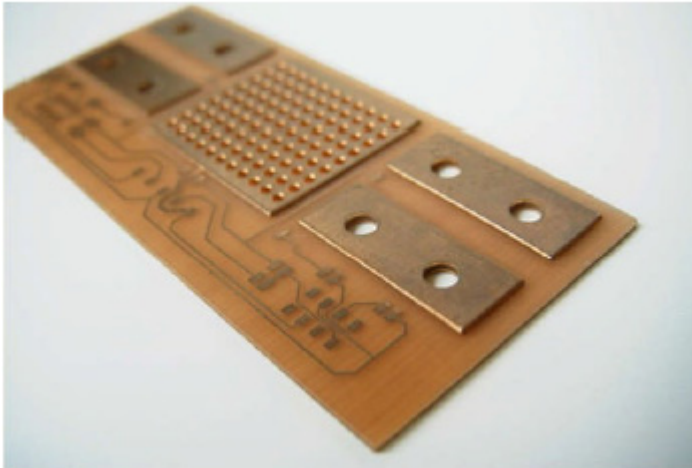
High Voltage Design



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Metal Core Design



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Chapter 1 Introduction to Metal Core Printed Circuits

Today's advanced electronics require higher power levels and larger heat removal from the denser chip packaging. Typical printed circuit technology will not disperse enough heat to satisfy these newer designs nor does it have low enough CTE numbers to properly place higher count BGA without reliability problems. Advanced metal cores, as well as